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**LED ARRAY**

**LA92B/EG.YG-1**

**DATA SHEET**

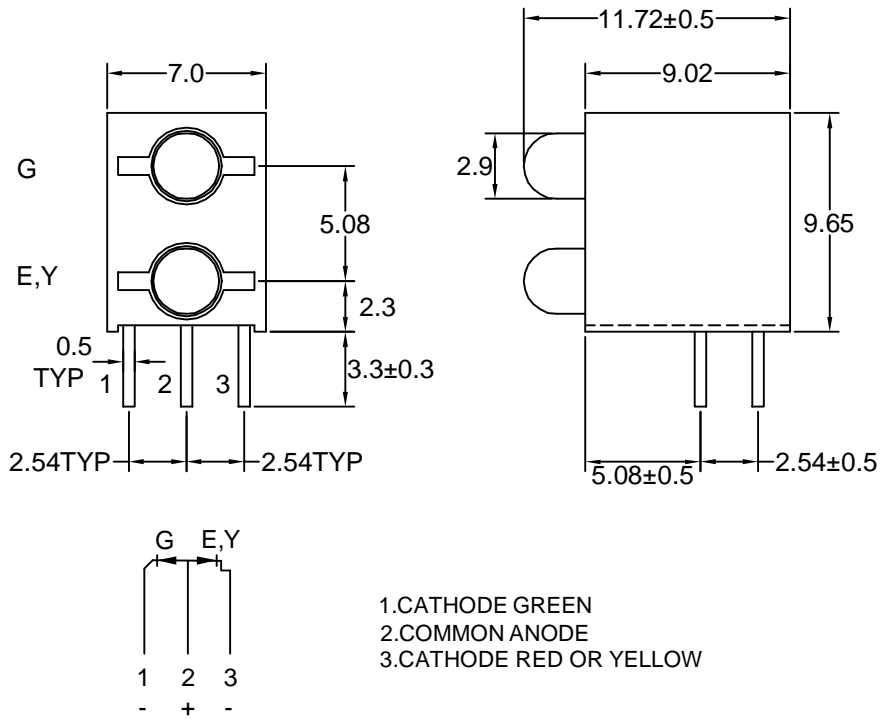
DOC. NO : QW0905-LA92B/EG.YG-1

REV. : A

DATE : 04 - Jan - 2005

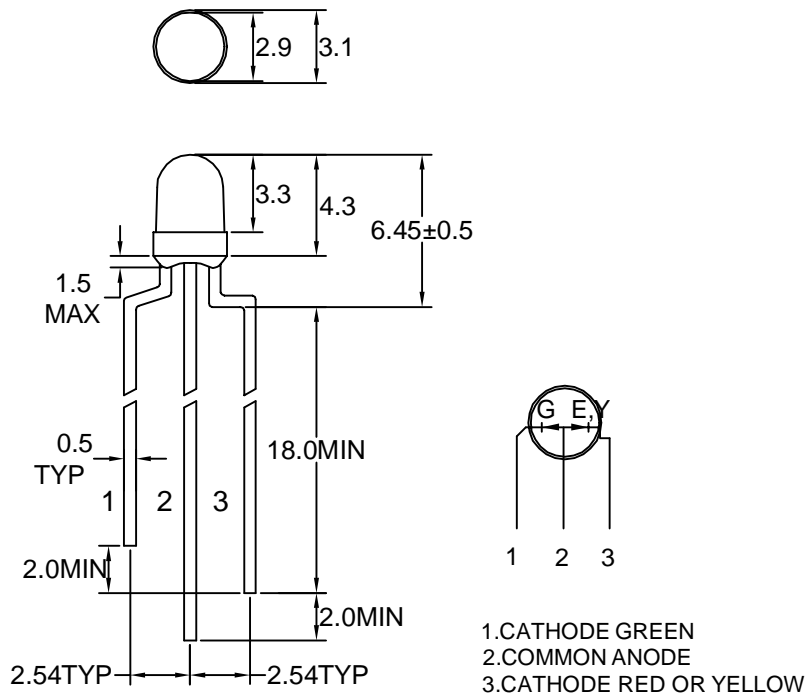


### Package Dimensions



- 1.CATHODE GREEN
- 2.COMMON ANODE
- 3.CATHODE RED OR YELLOW

### LEG2692/R1 LYG2692/R1



- 1.CATHODE GREEN
- 2.COMMON ANODE
- 3.CATHODE RED OR YELLOW

Note : 1.All dimension are in millimeter tolerance is ±0.25mm unless otherwise noted.  
2.Specifications are subject to change without not



## Absolute Maximum Ratings at Ta=25

Parameter	Symbol	Ratings			UNIT
		E	Y	G	
Forward Current	IF	30	20	30	mA
Peak Forward Current Duty 1/10@10KHz	IFP	120	80	120	mA
Power Dissipation	PD	100	60	100	mW
Reverse Current @5V	Ir	10	10	10	μ A
Operating Temperature	Topr	-40 ~ +85			
Storage Temperature	Tstg	-40 ~ +100			
Soldering Temperature	Tsol	Max 260 for 5 sec Max (2mm from body)			

## Typical Electrical &amp; Optical Characteristics (Ta=25 )

PART NO	MATERIAL	COLOR		Peak wave length Pnm	Spectral halfwidth nm	Forward voltage @20mA(V)		Luminous intensity @10mA(mcd)		Viewing angle 2 1/2 (deg)
		Emitted	Lens			Min.	Max.	Min.	Typ.	
LA92B/EG.YG-1	GaAsP/GaP	Orange	White Duffused	635	45	1.7	2.6	0.8	1.2	36
	GaP	Green		565	30	1.7	2.6	1.2	2.0	36
	GaAsP/GaP	Yellow	White Duffused	585	35	1.7	2.6	1.8	4.5	36
	GaP	Green		565	30	1.7	2.6	1.2	2.0	36

Note : 1.The forward voltage data did not including  $\pm 0.1V$  testing tolerance.  
2. The luminous intensity data did not including  $\pm 15\%$  testing tolerance.



### Typical Electro-Optical Characteristics Curve

E CHIP

Fig.1 Forward current vs. Forward Voltage

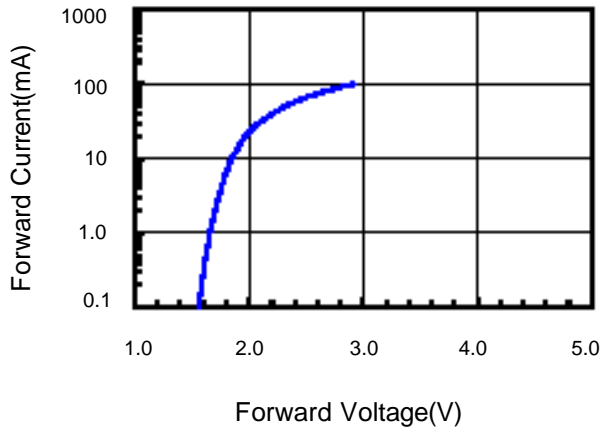


Fig.2 Relative Intensity vs. Forward Current

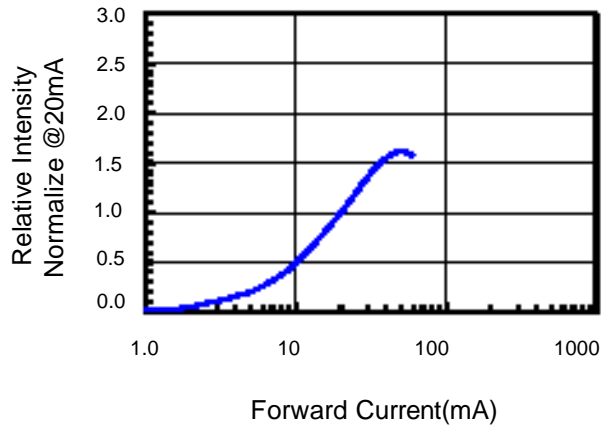


Fig.3 Forward Voltage vs. Temperature

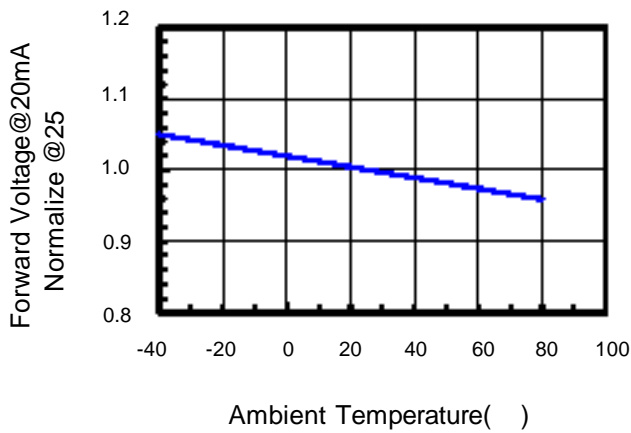


Fig.4 Relative Intensity vs. Temperature

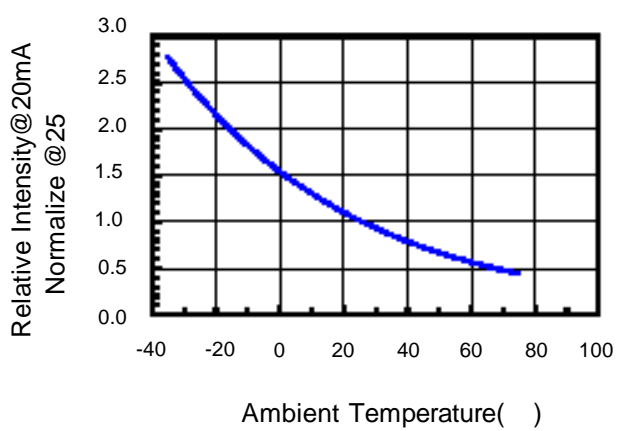
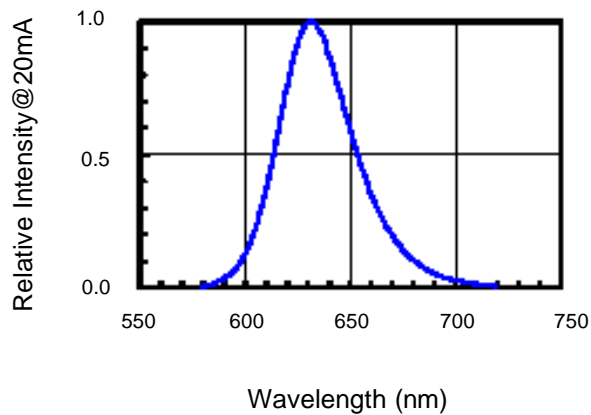


Fig.5 Relative Intensity vs. Wavelength





### Typical Electro-Optical Characteristics Curve

Y CHIP

Fig.1 Forward current vs. Forward Voltage

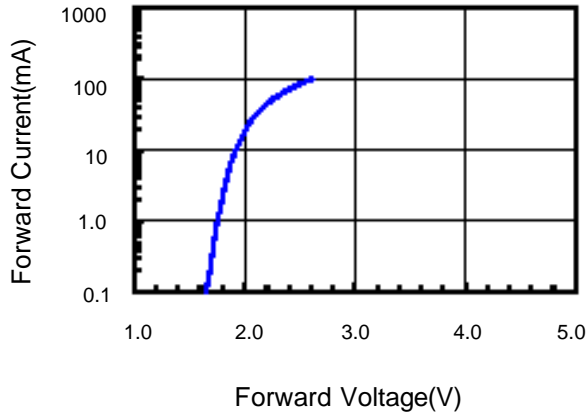


Fig.2 Relative Intensity vs. Forward Current

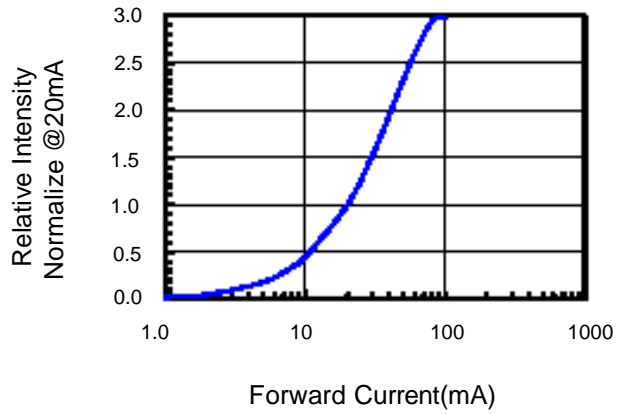


Fig.3 Forward Voltage vs. Temperature

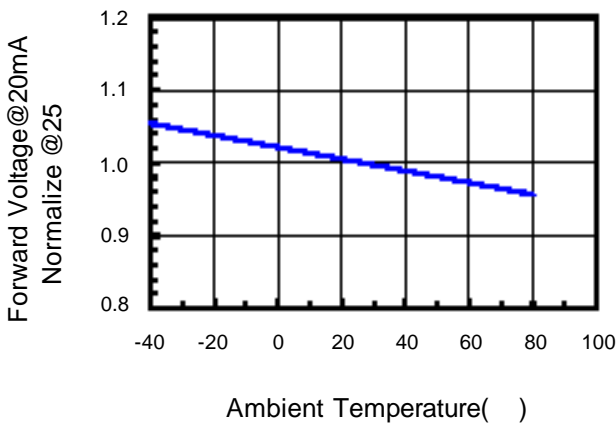


Fig.4 Relative Intensity vs. Temperature

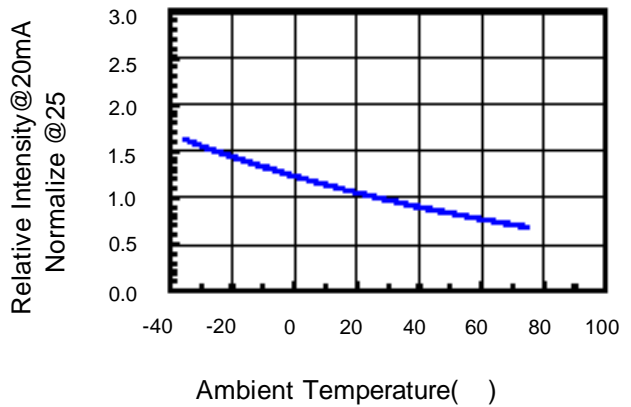
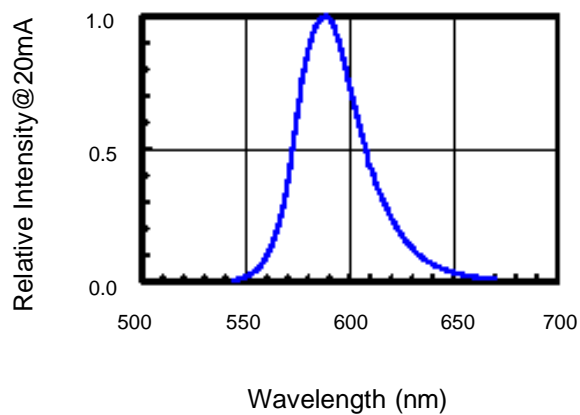


Fig.5 Relative Intensity vs. Wavelength





### Typical Electro-Optical Characteristics Curve

G CHIP

Fig.1 Forward current vs. Forward Voltage

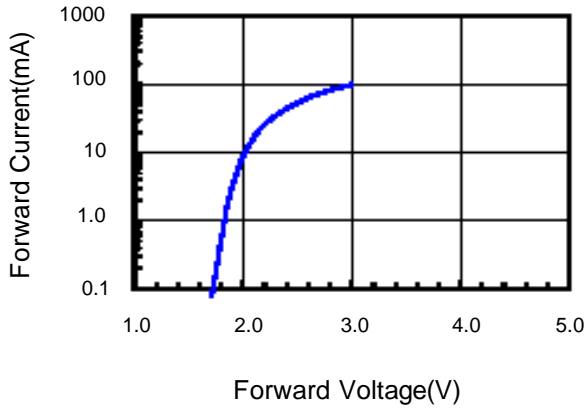


Fig.2 Relative Intensity vs. Forward Current

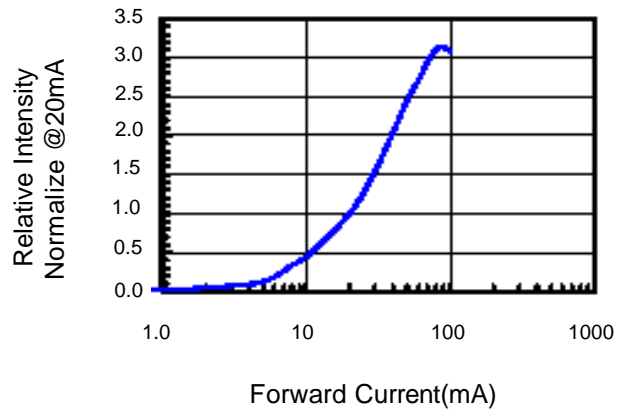


Fig.3 Forward Voltage vs. Temperature

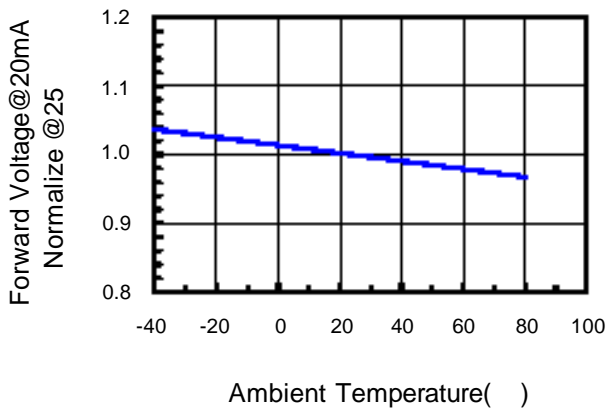


Fig.4 Relative Intensity vs. Temperature

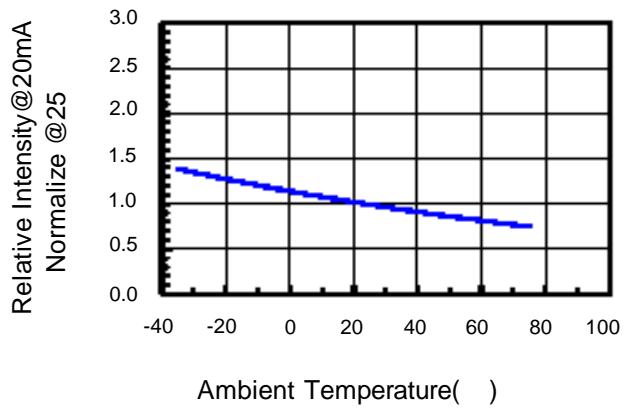
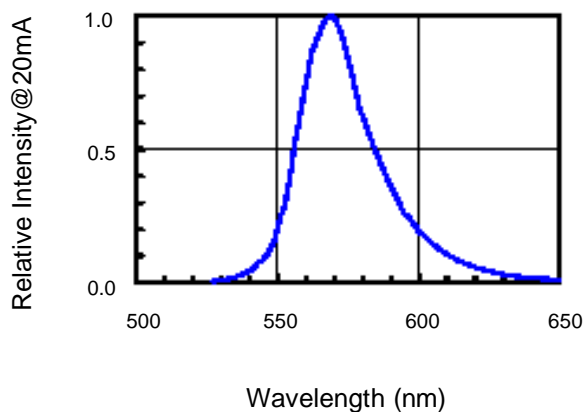


Fig.5 Relative Intensity vs. Wavelength





Reliability Test:

Test Item	Test Condition	Description	Reference Standard
Operating Life Test	1.Under Room Temperature 2.If=20mA 3.t=1000 hrs (-24hrs, +72hrs)	This test is conducted for the purpose of determining the resistance of a part in electrical and thermal stressed.	MIL-STD-750: 1026 MIL-STD-883: 1005 JIS C 7021: B-1
High Temperature Storage Test	1.Ta=105 ±5 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of high temperature for hours.	MIL-STD-883:1008 JIS C 7021: B-10
Low Temperature Storage Test	1.Ta=-40 ±5 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of low temperature for hours.	JIS C 7021: B-12
High Temperature High Humidity Test	1.Ta=65 ±5 2.RH=90 %-95% 3.t=240hrs ±2hrs	The purpose of this test is the resistance of the device under tropical for hours.	MIL-STD-202:103B JIS C 7021: B-11
Thermal Shock Test	1.Ta=105 ±5 & -40 ±5 (10min) (10min) 2.total 10 cycles	The purpose of this is the resistance of the device to sudden extreme changes in high and low temperature.	MIL-STD-202: 107D MIL-STD-750: 1051 MIL-STD-883: 1011
Solder Resistance Test	1.T.Sol=260 ±5 2.Dwell time= 10 ±1sec.	This test intended to determine the thermal characteristic resistance of the device to sudden exposures at extreme changes in temperature when soldering the lead wire.	MIL-STD-202: 210A MIL-STD-750: 2031 JIS C 7021: A-1
Solderability Test	1.T.Sol=230 ±5 2.Dwell time=5 ±1sec	This test intended to see soldering well performed or not.	MIL-STD-202: 208D MIL-STD-750: 2026 MIL-STD-883: 2003 JIS C 7021: A-2